WHAT IS CLAIMED IS:

1. A copper-clad laminate comprising a copper foil having a surface roughness in terms of Rz of 1 μm or less and an aromatic polyimide film placed thereon, wherein the copper foil is bonded to the polyimide film at a bonding strength of 500 N/m or higher and the polyimide film shows a light transmittance of 40% or higher for a light of wavelength of 600 nm and a haze of 30% or higher, the light transmittance and haze being values measured after the copper foil is removed by etching.

2. The copper-clad laminate of claim 1, wherein the polyimide film has a thermoplastic surface at least on one side.

3. The copper-clad laminate of claim 2, wherein the polyimide film comprises a polyimide substrate film having no glass transition temperature at temperatures of lower than 340°C and at least one thermoplastic polyimide film placed on the polyimide substrate film, the thermoplastic polyimide film having a glass transition temperature in the range of 180 to 275°C.

4. The copper-clad laminate of claim 1, which shows a bonding strength of 285 N/m or higher, the bonding strength being measured between the copper foil and the polyimide film after the laminate is kept at 150°C for 1,000 hours.

5. The copper-clad laminate of claim 1, which shows a bonding strength of 80% or higher of an initial bonding strength between the copper foil and the polyimide film, the former bonding strength being measured after the laminate is kept at 150°C for 1,000 hours.

6. The copper-clad laminate of claim 1, wherein the copper foil has an adhesive surface.

7. The copper-clad laminate of claim 6, wherein the adhesive surface is produced by placing a coupling agent on the copper foil.

8. The copper-clad laminate of claim 6, wherein the coupling agent is a silane-coupling agent.

9. The copper-clad laminate of claim 1, wherein the copper foil is in the form of a continuous film having a gloss of 360% or higher in a longitudinal direction thereof and a gloss of 310% or higher in a width direction thereof, the glosses being measured at an incident angle of 60°.

10. A process for manufacturing a copper-clad laminate of claim 1, which comprises the steps of:

preparing a copper foil having a surface roughness in terms of Rz of 1 μm or less and an adhesive surface and an aromatic polyimide film comprising a polyimide substrate film having no glass transition temperature at temperatures of lower than 340°C and at least one thermoplastic polyimide film placed on the polyimide substrate film, the thermoplastic polyimide film having a glass transition temperature in the range of 200 to 275°C;

placing the thermoplastic polyimide film of the aromatic polyimide film on the adhesive surface of the copper foil; and

heating the thermoplastic polyimide film and the copper foil at a temperature of higher than the glass transition temperature of the thermoplastic polyimide film but not higher than 400°C under pressure.

11. The process of claim 10, wherein the step of heating the thermoplastic polyimide film and the copper foil is performed by means of a double belt press.

12. The process of claim 10, wherein the adhesive surface of the copper foil is produced by placing a coupling agent on the copper foil.

13. A copper-clad laminate comprising a copper layer and an aromatic polyimide film placed thereon, wherein the copper layer is bonded to the polyimide film at a bonding strength of 500 N/m or higher under the condition that the bonding strength after heating at 150°C for 1,000 hours is 285 N/m or higher, and the polyimide film shows a light transmittance of 40% or higher for a light of wavelength of 600 nm and a haze of 30% or higher, the light transmittance and haze being values measured after the copper layer is removed by etching.